

1765



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

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Amendment, Commissioner for Patents,
Washington, D.C. 20231 on April 17, 2003
(Date of Deposit)

Harold C. Moore

Name of person mailing Document or Fee

[Signature]
Signature

April 17, 2003

Date of Signature

Re: Application of: Charles E. May
 Serial No.: 09/943,196
 Filed: August 30, 2001
 For: Arrangement and Method for Fabricating A
 Semiconductor Wafer
 Group Art Unit: 1765
 Examiner: Lynette T. Umez-Eronini
 Our Docket No.: 01-146 (1003-0606)

TRANSMITTAL OF RESPONSE TO OFFICE ACTION

Please find for filing in connection with the above patent application the
following:

1. Response to Office Action; and
2. One (1) return post card.

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* The fee has been calculated as shown below.

CLAIMS AS AMENDED				
	Claims Remaining After Amendment	Highest No. Paid For	Fee Calculation	Addit Fee
Total Claims	17	20	0 X 18	\$ 0.00
Independent Claims	2	3	0 X 84	\$ 0.00
Total Additional Fee Required				\$ 0.00

Please charge any fee deficiency, or credit any overpayment, to Deposit Account No. 13-0014; but not to include any payment of issue fees.

Respectfully Submitted,

MAGINOT, MOORE & BOWMAN



April 17, 2003

Harold C. Moore
Registration No. 37,892
Bank One Center/Tower
111 Monument Circle, Suite 3000
Indianapolis, Indiana 46204-5115

Enclosures



#3/A
4/24/03

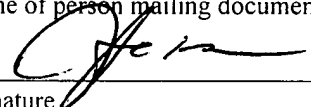
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RESPONSE TO OFFICE ACTION

Sir:

Please charge any fee deficiency or credit any overpayment to Deposit Account

No. 13-0014. In response to the Office Action dated January 17, 2003 for the above-
identified patent application, please amend the application as follows: